

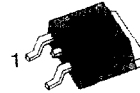
SGW5N60RUF

CO-PAK IGBT

FEATURES

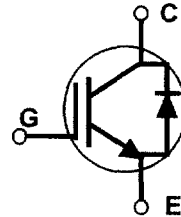
- * Short Circuit rated 10uS @Tc=100°C
- * High Speed Switching
- * Low Saturation Volatge
 - : $V_{CE(sat)} = 2.0\text{ V @ } I_c=5\text{A}$
- * High Input Impedance
- * CO-PAK, IGBT with FRD
 - : $T_{rr} = 37\text{nS (Typ.)}$

D²-PAK



APPLICATIONS

- * AC & DC Motor controls
- * General Purpose Inverters
- * Robotics , Servo Controls
- * Power Supply
- * Lamp Ballast



ABSOLUTE MAXIMUM RATINGS

Symbol	Characteristics	Rating	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_c = 25^\circ\text{C}$	8	A
	Collector Current @ $T_c = 100^\circ\text{C}$	5	A
$I_{CM(1)}$	Pulsed Collector Current	15	A
I_F	Diode Continuous Forward Current @ $T_c = 100^\circ\text{C}$	8	A
I_{FM}	Diode Maximum Forward Current	56	A
P_D	Maximum Power Dissipation @ $T_c = 25^\circ\text{C}$	60	W
	Maximum Power Dissipation @ $T_c = 100^\circ\text{C}$	25	W
Tsc	Short Circuit Withstand Time	10	μS
T_j	Operating Junction Temperature	-55 ~ 150	$^\circ\text{C}$
Tstg	Storage Temperature Range	-55 ~ 150	$^\circ\text{C}$
TL	Maximum Lead Temp. For Soldering	300	$^\circ\text{C}$
	Purposes, $\frac{1}{8}$ " from case for 5 seconds		

Notes: (1) Repetitive rating : Pulse width limited by max. junction temperature

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ELECTRICAL CHARACTERISTICS (IGBT PART)

(T_c=25 °C, Unless Otherwise Specified)

Symbol	Characteristics	Test Conditions	Min	Typ	Max	Units
BV _{CES}	C - E Breakdown Voltage	V _{GE} = 0V , I _C = 250 μA	600	-	-	V
ΔV _{CES} /ΔT _J	Temperature Coeff. of Breakdown Voltage	V _{GE} = 0V , I _C = 1mA	-	0.6	-	V/°C
V _{GE(th)}	G - E threshold voltage	I _C = 5mA , V _{CE} = V _{GE}	5.0	6.0	8.0	V
I _{CES}	Collector cutoff Current	V _{CE} = V _{CES} , V _{GE} = 0V	-	-	250	μA
I _{GES}	G - E leakage Current	V _{GE} = V _{GES} , V _{CE} = 0V	-	-	100	nA
V _{CE(sat)}	Collector to Emitter saturation voltage	I _C =5A, V _{GE} = 15V	-	2.0	2.7	V
		I _C =8A, V _{GE} = 15V	-	2.5	-	V
C _{ies}	Input capacitance	V _{GE} = 0V , f = 1MHz	-	337	-	pF
C _{oes}	Output capacitance	V _{CE} = 30V	-	60	-	pF
C _{res}	Reverse transfer capacitance		-	13	-	pF
t _{d(on)}	Turn on delay time	V _{CC} = 300V , I _C = 5A	-	9	-	nS
t _r	Turn on rise time	V _{GE} = 15V	-	18	-	nS
t _{d(off)}	Turn off delay time	R _G = 40 Ω	-	46	75	nS
t _f	Turn off fall time	Inductive Load	-	140	280	nS
E _{on}	Turn on Switching Loss		-	80	-	μJ
E _{off}	Turn off Switching Loss		-	100	-	μJ
E _{ts}	Total Switching Loss		-	180	270	μJ
T _{sc}	Short Circuit withstand Time	V _{CC} = 300V, V _{GE} = 15V @T _c = 100 °C	10	-	-	μS
Q _g	Total Gate Charge	V _{CC} = 300V	-	24	36	nC
Q _{ge}	Gate-Emitter Charge	V _{GE} = 15V	-	7	10	nC
Q _{gc}	Gate-Collector Charge	I _C = 5A	-	8	12	nC

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CO-PAK IGBT

ELECTRICAL CHARACTERISTICS (DIODE PART)

(T_c=25°C, Unless Otherwise Specified)

Symbol	Characteristics	Test Conditions	Min	Typ	Max	Units	
V _{FM}	Diode Forward Voltage	I _F =8.0A	T _c = 25°C	-	1.4	1.7	V
			T _c = 100°C	-	1.3	-	
T _{rr}	Diode Reverse Recovery Time		T _c = 25°C	-	37	55	nS
			T _c = 100°C	-	55	-	
I _{rr}	Diode Peak Reverse Recovery Current	I _F =8.0A, V _R =200V -di/dt=200A/μS	T _c = 25°C	-	3.5	5.0	A
			T _c = 100°C	-	4.5	-	
Q _{rr}	Diode Reverse Recovery Charge		T _c = 25°C	-	65	138	nC
			T _c = 100°C	-	124	-	

THERMAL RESISTANCE

Symbol	Characteristics	Min	Typ	Max	Units
R _{θJC}	Junction-to-Case (IGBT)	-	-	2.0	°C/W
R _{θJC}	Junction-to-Case (DIODE)	-	-	3.5	°C/W
R _{θJA}	Junction-to-Ambient (PCB mount)	-	-	40	°C/W

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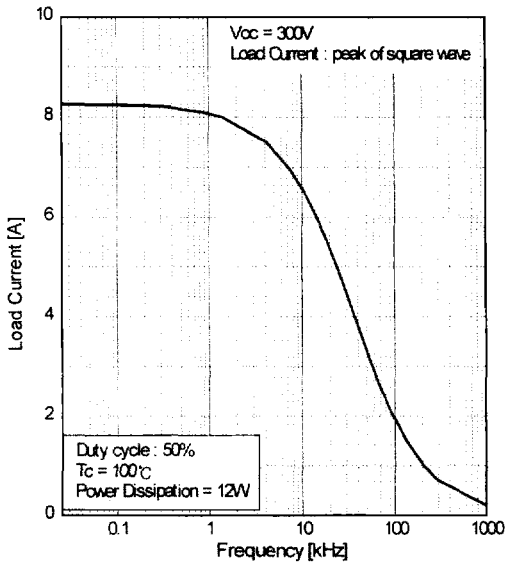


Fig.1 Typical Load Current vs. Frequency

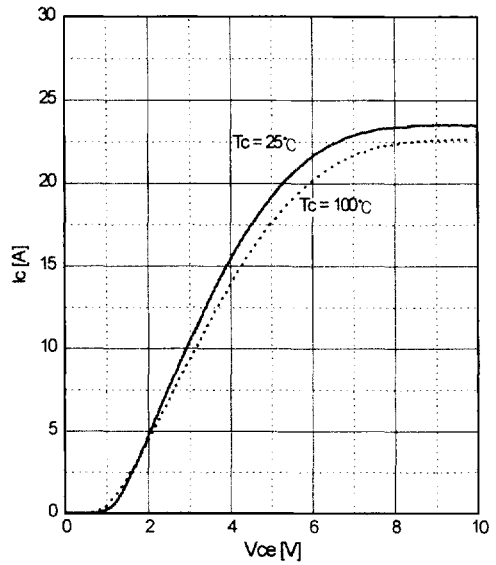


Fig.2 Typical Output Characteristics

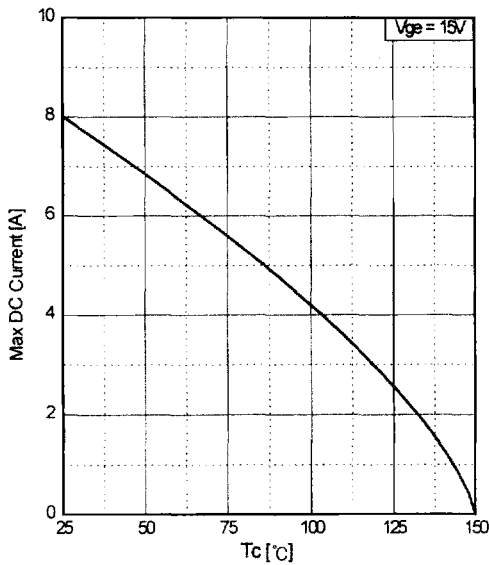


Fig.3 Maximum Collector Current vs. Case Temperature

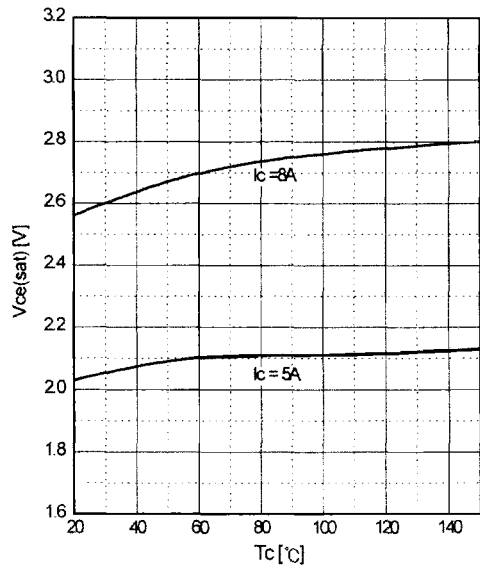


Fig.4 Collector to Emitter Voltage vs. Case Temperature

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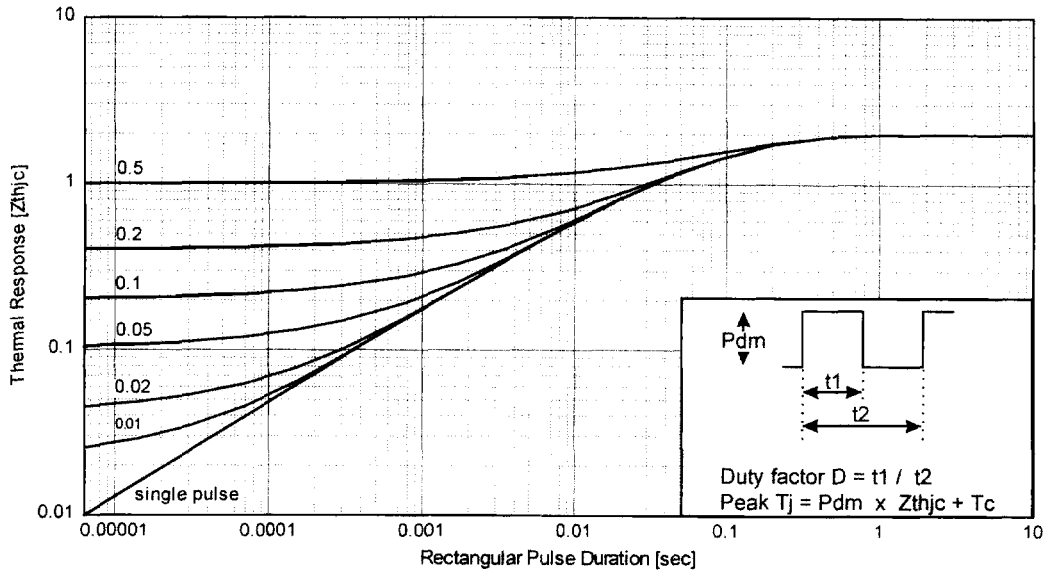


Fig.5 Maximum Effective Transient Thermal Impedance, Junction to Case

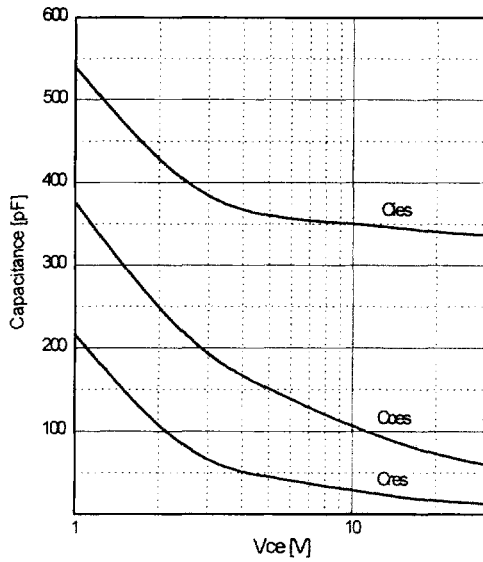


Fig.6 Typical Capacitance vs. Collector to Emitter Voltage

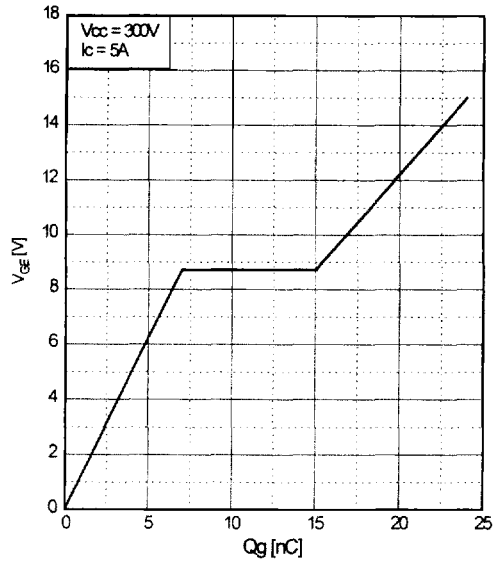


Fig.7 Typical Gate Charge vs. Gate to Emitter Voltage

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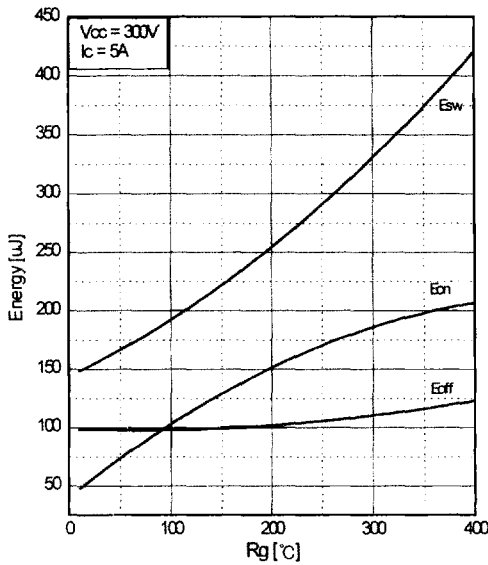


Fig.8 Typical Switching Loss vs. Gate Resistance

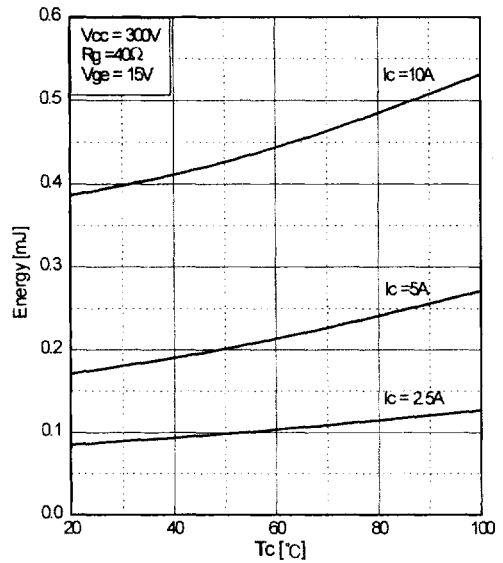


Fig.9 Typical Switching Loss vs. Case Temperature

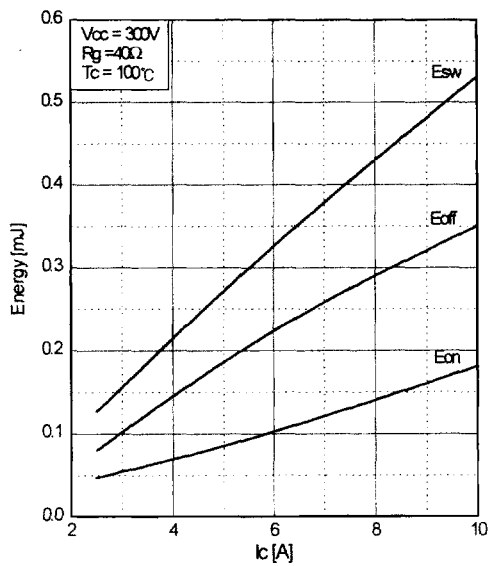


Fig.10 Typical Switching loss vs. Collector to Emitter Current

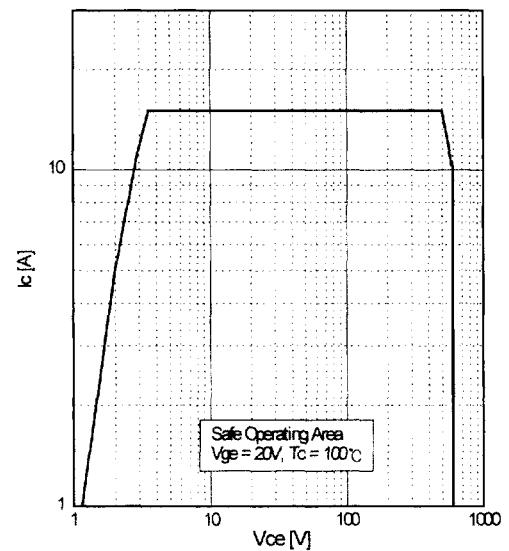


Fig.11 Turn-off SOA

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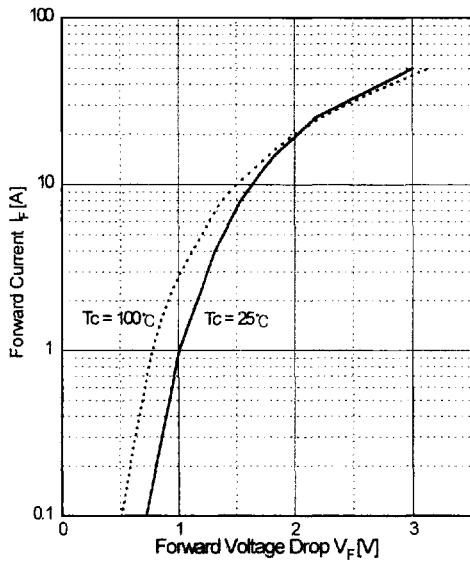


Fig.12 Typical Forward Voltage Drop vs. Forward Current

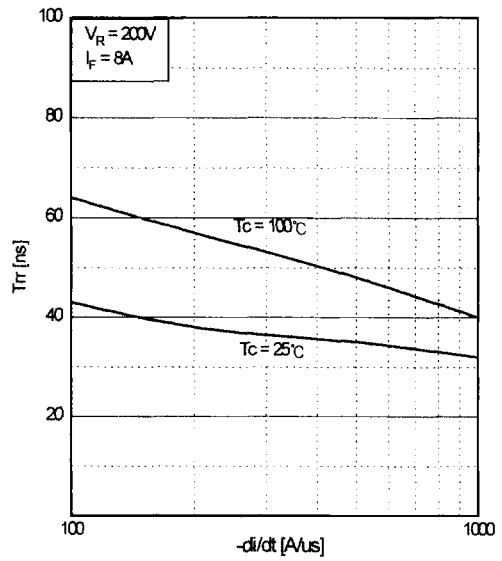


Fig.13 Typical Reverse Recovery Time vs. di/dt

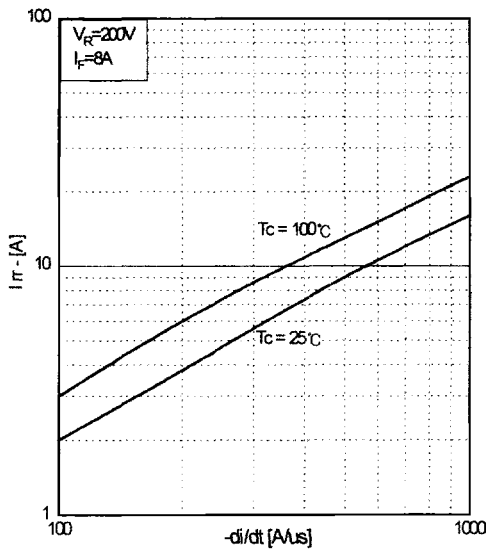


Fig.14 Typical Reverse Recovery Current vs. di/dt

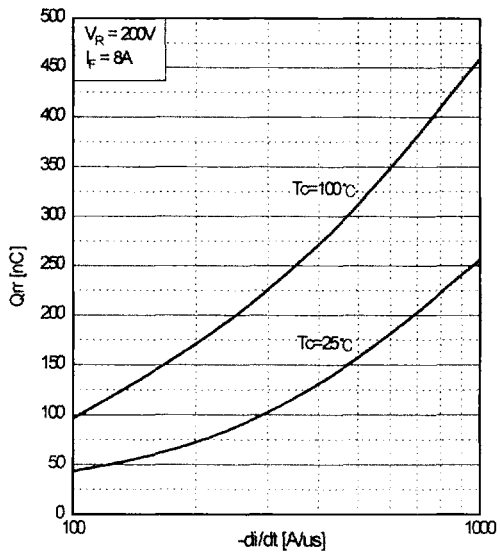


Fig.15 Typical Stored Charge vs. di/dt